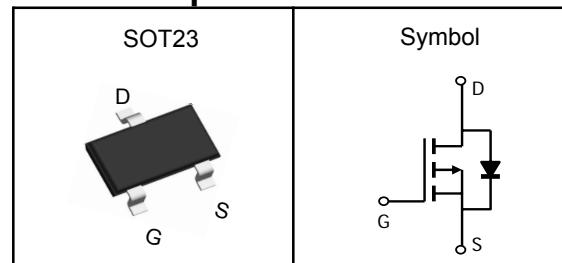


P-Channel Enhancement Mode MOSFET

Features

- Low R_{dson} for low conduction loss
- Reliable and Rugged
- ROHS Compliant & Halogen-Free

Pin Description



Applications

- Power Management in Desktop Computer
- DC/DC Converters

V_{DSS}	-40	V
$R_{DS(ON)-Typ}$	55	$\text{m}\Omega$
I_D	-2.9	A

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$, Unless Otherwise Noted)

Symbol	Parameter	P-Channel	Unit
V_{DSS}	Drain-Source Voltage	-40	V
V_{GSS}	Gate-Source Voltage	± 20	V
T_J	Maximum Junction Temperature	-55 to 150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$I_{DM}^{①}$	Pulse Drain Current Tested	-11.6	A
I_D	Continuous Drain Current	-2.9	A
P_D	Maximum Power Dissipation	1.0	W

Thermal Characteristics

Symbol	Parameter	Rating	Unit
$R_{\theta JA}^{③}$	Thermal Resistance-Junction to Ambient	125	$^\circ\text{C}/\text{W}$

Note ① : Max. current is limited by bonding wire.

Note ② : UIS tested and pulse width are limited by maximum junction temperature 150°C.

Note ③ : Surface Mounted on 1in² FR-4 board with 1oz.

P-Channel Enhancement Mode MOSFET

Electrical Characteristics ($T_J=25^\circ\text{C}$, Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
Static Electrical Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_{\text{D}}=-250\mu\text{A}$	-40	---	---	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}}=-40\text{V}$, $V_{\text{GS}}=0\text{V}$	---	---	-1	μA
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$, $I_{\text{D}}=-250\mu\text{A}$	-1.0	---	-2.5	V
I_{GSS}	Gate Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA
$R_{\text{DS(ON)}}$	Drain-Source On-state Resistance	$V_{\text{GS}}=-10\text{V}$, $I_{\text{D}}=-2\text{A}$	---	55	68	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}$, $I_{\text{D}}=-1\text{A}$	---	75	100	$\text{m}\Omega$
g_{fs}	Forward Transconductance	$V_{\text{DS}}=-10\text{V}$, $I_{\text{D}}=-1\text{A}$	---	3.0	---	S
Dynamic Characteristics^⑤						
C_{iss}	Input Capacitance	$V_{\text{GS}}=0\text{V}$, $V_{\text{DS}}=-25\text{V}$, Freq.=1MHz	---	600	---	pF
C_{oss}	Output Capacitance		---	60	---	
C_{rss}	Reverse Transfer Capacitance		---	43	---	
$T_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{DD}}=-20\text{V}$, $V_{\text{GS}}=-10\text{V}$, $R_{\text{G}}=6\Omega$, $I_{\text{D}}=-1\text{A}$	---	19	---	nS
T_r	Turn-on Rise Time		---	9	---	
$T_{\text{d(off)}}$	Turn-off Delay Time		---	45	---	
T_f	Turn-off Fall Time		---	5	---	
Q_g	Total Gate Charge	$V_{\text{DS}}=-32\text{V}$, $V_{\text{GS}}=-10\text{V}$, $I_{\text{D}}=-2\text{A}$	---	6.4	---	nC
Q_{gs}	Gate-Source Charge		---	0.5	---	
Q_{gd}	Gate-Drain Charge		---	2.7	---	
Source-Drain Characteristics ($T_J=25^\circ\text{C}$)						
$V_{\text{SD}}^{④}$	Diode Forward Voltage	$V_{\text{GS}}=0\text{V}$, $I_{\text{S}}=-1\text{A}$, $T_J=25^\circ\text{C}$	---	---	-1	V

Note ④ : Pulse test (pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$).

Note ⑤ : Guaranteed by design, not subject to production testing.

P-Channel Enhancement Mode MOSFET

Typical Characteristics

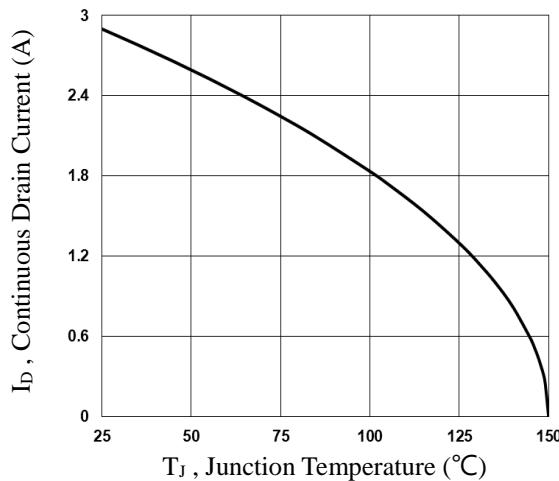


Fig.1 Continuous Drain Current vs. T_J

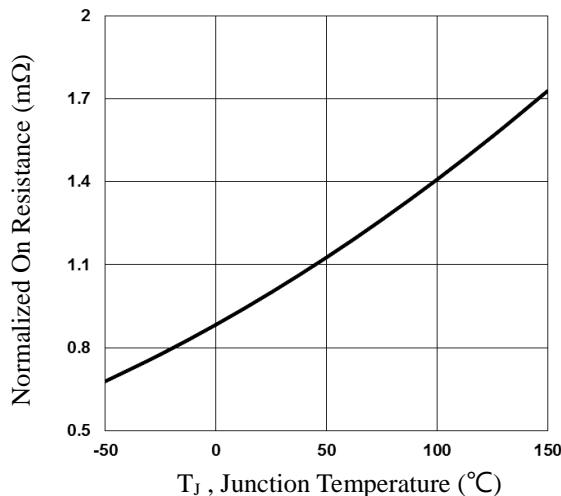


Fig.2 Normalized RDSON vs. T_J

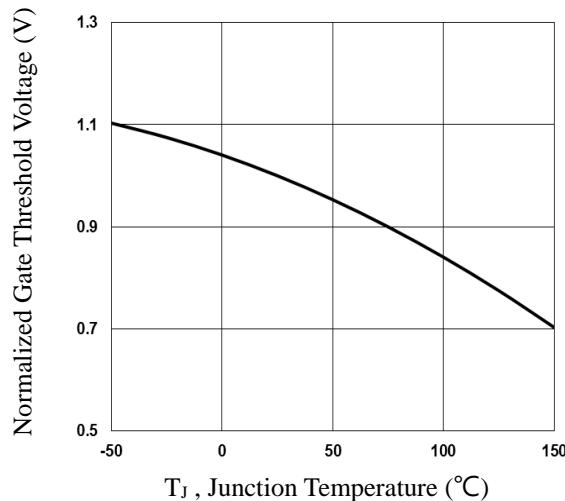


Fig.3 Normalized V_{th} vs. T_J

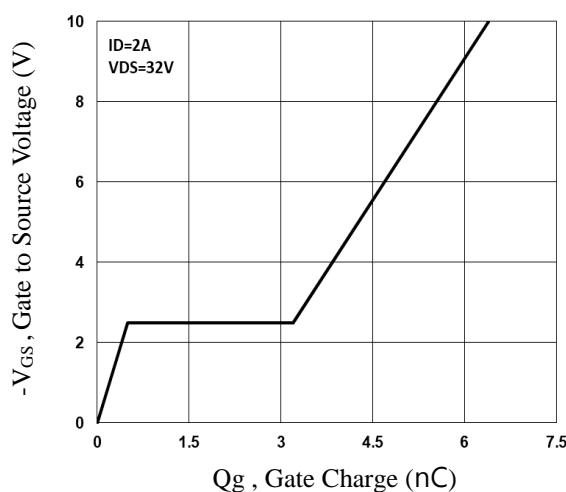


Fig.4 Gate Charge Waveform

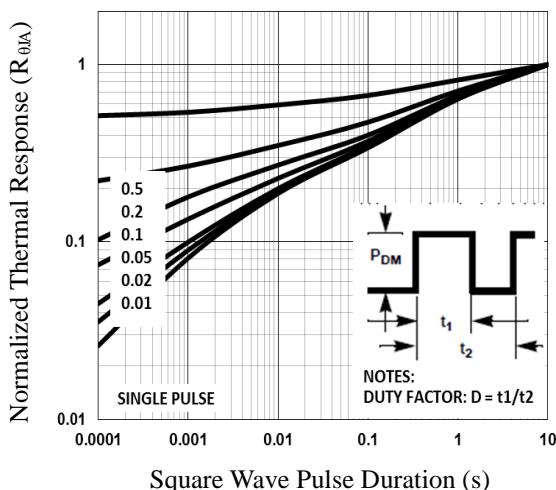


Fig.5 Normalized Transient Impedance

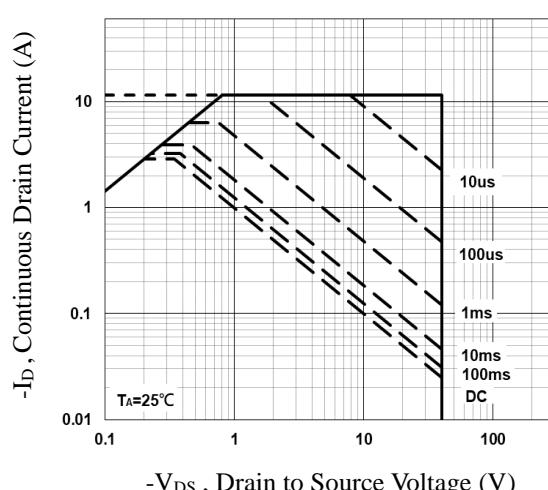


Fig.6 Maximum Safe Operation Area

P-Channel Enhancement Mode MOSFET

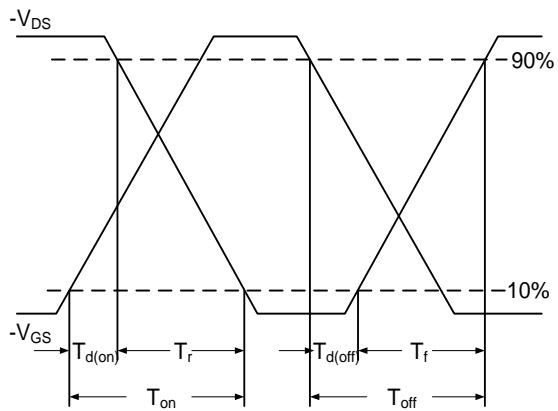


Fig.7 Switching Time Waveform

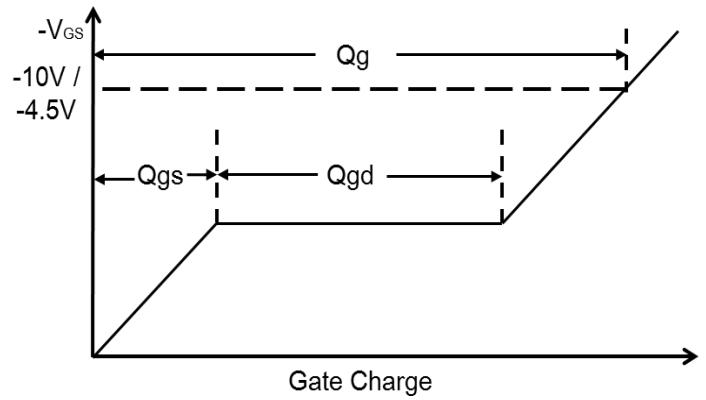
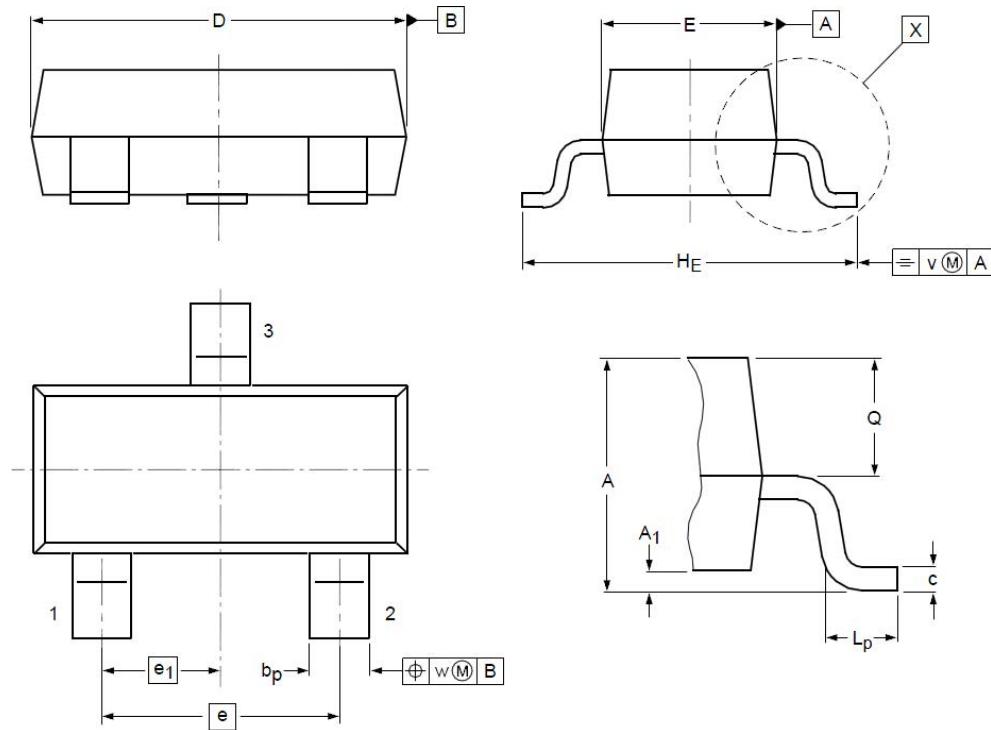


Fig.8 Gate Charge Waveform

P-Channel Enhancement Mode MOSFET

SOT23 Package Outline Dimensions



Symbol	Dimensions (unit:mm)			Symbol	Dimensions (unit:mm)		
	Min	Typ	Max		Min	Typ	Max
A	0.90	1.05	1.20	e ₁	--	0.95	--
A ₁	0.01	0.05	0.10	H _E	2.10	2.40	2.50
b _p	0.38	0.42	0.48	L _P	0.40	0.50	0.60
c	0.09	0.13	0.15	Q	0.45	0.49	0.55
D	2.80	2.92	3.00	V	--	0.20	--
E	1.20	1.33	1.40	W	--	0.10	--
e	--	1.90	--				